

Page 4, replace the paragraph, beginning on line 27, bridging pages 4 and 5, as follows:

--According to a sixth aspect of the invention, the semiconductor device further comprises a plurality of semiconductor chips each of which includes the plurality of processing elements and the switcher, and at least one inter-switcher which connects the semiconductor chips to each other. The configuration is desirable to constitute a plurality of packages by using many semiconductor chips.--.

Page 5, replace the paragraph, beginning on line 4, as follows:

--According to a seventh aspect of the invention, the plurality of semiconductor chips and the inter-switcher are implemented two-dimensionally. In addition, the inter-switcher is located in one of the plurality of semiconductor chips, and the semiconductor chips are implemented three-dimensionally. Also, each of the switcher and the inter-switcher may be a circuit switching.--.

Page 10, replace the paragraph, beginning on line 16, as follows:

--The package 301 and the plurality of the packages 201 and 202 are connected to each other via an extra communication port 320 which is located outside the package. This is the difference between the system LSI shown in Fig. 4 and the system LSI shown in Fig. 5. Also, the package 301 includes an intra-

switcher 313 which internally connects a plurality of processing modules 311 and 312, and an inter-switcher 314 which connects the packages. The processing modules 311 and 312 include network interfaces 315 and 316, respectively.

Page 11, replace the paragraph, beginning on line 10, as follows:

- In Fig. 6, a system LSI is shown which is composed of a single chip module produced by forming a die 410 made from a silicon wafer 400 in a package 420. In the die 410, there are a switcher 412 located at the center of the die and a plurality of processing modules 411 located around the switcher. The die can perform the same functions as the system LSI shown in Fig. 3;

replace the paragraph, beginning on line 26, bridging pages 11 and 12, as follows:

- The package 500 is based on a multi-chip module forming a plurality of semiconductor chips 610 on a surface of a package substrate 501. Around the multi-chip module, sealing is done by a sealing resin 602. Further, a sealing resin 603 is used to seal the substrate 501 and the sealing resin 602. As a result, a light signal 620 from a light emitting element 611 is confined inside the sealing resin 602.

IN THE CLAIMS:

Amend claim 1 as follows:

- 1. (amended) A semiconductor device comprising:  
a plurality of processing elements; and